

# 2935

Broadband plasma optical patterned wafer inspection system discovers defects that affect the yield and reliability of logic chips

## BENEFITS:

The 2935 provides high sensitivity discovery and binning of critical defects across a broad range of process layers, material types and process stacks. The 2935 helps logic manufacturers:

- Accelerate R&D and ramp cycle time through characterization and optimization of new processes, design nodes and devices
- Implement defect reduction strategies to meet chip quality requirements
- Accelerate yield learning by providing accurate, actionable data on yield-critical defects
- Detect and characterize defect issues at optimal cost of ownership

## TECHNOLOGIES:

- Tunable DUV, UV, visible broadband illumination source
- Selectable optical apertures
- Low-noise sensor
- Design-aware technologies, including pin•point™ and super•cell™
- Advanced defect detection algorithms
- Automated defect binning

## APPLICATIONS:

- Defect discovery for R&D and ramp
- Characterization and debug of defect issues
- Inline monitoring of critical layers requiring high sensitivity
- Process window discovery and qualification



## MARKET:

Chip manufacturing  
advanced design node logic devices

## PLATFORM:

- Customizable configurations
- Extendible
- Upgradeable
- 300mm wafers